

OE-A Members – Companies



- O** 3DMA (DE)
- A** ABeetle (TW)
A.F. Suter (GB)
Adphos Digital Printing (DE)
Almax (US)
Apeva (DE)
Alpha Assembly Solutions (US)
American Semiconductor (US)
ARM Ltd. (GB)
Armor (FR)
- B** BASF Coatings Schweiz (CH)
BASF New Business (DE)
Brewer Science (US)
Brückner Maschinenbau (DE)
BST Eltromat International (DE)
- C** CCI Eurolam (DE)
Ceradrop (FR)
Chasm Advanced Materials (US)
Classic Stripes (IN)
Coatema Coating Machinery (DE)
CondAlign (NO)
Continental Automotive (DE)
Copprint (IL)
Coruna Printed Electronics (CH)
Cynora (DE)
- D** db-matik (DE)
Dowa HD Europe (DE)
Dracula Technologies (FR)
DuPont Advanced Materials (GB)
DuPont Teijin Films (GB)
- E** Elantas Europe (DE)
Elmeric (DE)
Emde development of light (DE)
Enfucell Flexible Electronics (CN)
Engineered Materials Systems (US)
EppsteinFoil (DE)
Eptatech (IT)
Ersa (DE)
Evonik Creavis (DE)
Exakt Advanced Technologies (DE)
- F** Felix Böttcher (DE)
Felix Schoeller Holding (DE)
Fleep Technologies (IT)
FlexEnable (GB)
Folex Coating (DE)
FUELIUM (ES)
Fujifilm Dimatix (US)
- G** Genes`Ink (FR)
Grapholymer (GB)
Greiner Technology & Innovation (AT)
GRT (DE)
Guangdong Juhua Printing (CN)
- H** Heliatek (DE)
Henkel (DE)
Heraeus Deutschland (DE)
Hoffmann + Krippner (DE)
HyPrint (DE)
- I** IBS Precision Engineering (NL)
IEE (LU)
IMAZ Technology (ES)
InnovationLab (DE)
InovisCoat (DE)
Inotec Barcode Security (DE)
Interlink Electronics (US)
Is it fresh (DE)
ISORG (FR)
- J** JT International Germany (DE)
JiLin OLED Material Tech (CN)
- K** Karl Knauer (DE)
Kelenn Technology (FR)
Kroenert (DE)
KSG (DE)
- L** Leonhard Kurz Stiftung (DE)
LG Technology Center Europe (DE)
LinkZill (CN)
Liquid X Printed Metals (US)
Lohmann (DE)
- M** MMP Premium Printing Center (DE)
M-Solv (GB)
Masar Printing and Publishing (AE)
Masterpress (PL)
Matti Technology (CH)
Merck (DE)
MSW (DE)
- N** Nanorbital Advanced Materials (IN)
NeuDrive (GB)
New Cable Corporation (FI)
NovaCentrix (US)
Novaled (DE)
nsm Norbert Schläfli (CH)
NXT (DE)
- O** OLEDWorks (DE)
Organic Electronic Technologies (GR)
Oxford Photovoltaics (GB)
- P** Papierfabrik Louisa (DE)
Piezotech (FR)
Plastic Logic Germany (DE)
Policrom Screens (IT)
PolyIC (DE)
PragmatIC Printing (GB)
Printcolor Deutschland (DE)
Printed Electronics (GB)
Protavic International (FR)
Pütz Folien (DE)
- R** Raynergy Tek (TW)
Reisewitz Beschichtungen (DE)
RK Siebdrucktechnik (DE)
ROWO Coating (DE)
- S** SABIC (NL)
SAES Getters (IT)
SAIT Europe (GB)
Saueressig (DE)
Schreiner Group (DE)
Screentec (FI)
Senorics (DE)
Seqens (FR)
SmartKem (UK)
Smit Thermal Solutions (NL)
Smooth & Sharp Corporation (TW)
Spin Corporation (JP)
SunaTech (CN)
Surteco Group (DE)
- T** Tacterion (DE)
Tagenea (ES)
Teknek (GB)
Temicon (DE)
Thin Film Electronics (NO)
Toyobo (JP)
TSE Troller (CH)
- V** VARTA Microbattery (DE)
VDL Flow (NL)
VFP Ink Technologies (FR)
- W** Werner Blase (DE)
Witte plusprint (DE)
- X** X-Celeprint (IE)
Xenon Corporation (US)
Xiamen Funano New Material (CN)
Xymox Technologies (US)
- Y** Ynvisible (PT)
YTC America (US)
- Z** ZEON (JP)

OE-A Members – Universities / Institutes



- A** AIST – Sensing Electronics Center (JP)
AIT – Austrian Institute of Technology (AT)
Aristotle University of Thessaloniki - LTFN (GR)
- B** BRNO University of Technology (CZ)
- C** C2MI (CA)
CEA Liten (FR)
Centi - Centre for Nanotechnology & Smart Materials (PT)
Centre Technique du Papier (CTP) (FR)
CIDETEC (ES)
Consiglio Nazionale delle Ricerche (CNR) (IT)
COPT Center (DE)
CPI - Centre for Process Innovation (GB)
CSEM (CH)
CSEM Brasil (BR)
CSIR (ZA)
- E** EMPA (CH)
Eurecat (ES)
- F** Fontys University of Applied Sciences (NL)
Fraunhofer ENAS (DE)
Fraunhofer FEP (DE)
Fraunhofer IAP (DE)
Fraunhofer IFAM (DE)
Fraunhofer ILT (DE)
Fraunhofer IPA (DE)
Fraunhofer ISC (DE)
Friedrich-Alexander-Universität – WW6 – i-Meet (DE)
Friedrich Schiller Universität Jena (DE)
- G** Georgia Tech – Center for Organic Photonics and Electronics (US)
- H** Hahn-Schickard – Institut für Mikroaufbautechnik (DE)
Hochschule der Medien - IAF, IAD (DE)
Hochschule Niederrhein (DE)
Holst Centre (NL)
- I** ICI – Printability and Graphic Communications Institute (CA)
IMB-CNM (CSIC) (ES)
Imec (BE)
Imperial College London – Centre for Plastic Electronics (GB)
Institut für Mikroelektronik Stuttgart (DE)
- IPC – Technical Centre of Plastics Engineering (FR)
ITRI - Industrial Technology Research Institute (TW)
- J** Joanneum Research (AT)
Johannes Kepler Universität Linz - LIOS (AT)
- K** Karlsruhe Institute of Technology - LTI (DE)
Konkuk University - FDRC (KR)
- L** Landshut University of Applied Sciences (DE)
Leitat Technological Center (ES)
Loughborough University (GB)
- M** MINES Saint-Étienne – Microelectronics - Center of Provence (FR)
Munich University of Applied Sciences – Print and Media Technologies (DE)
- N** NAITEC (ES)
National Research Council Canada (CA)
NPL - National Physics Laboratory (GB)
- O** Oulu University of Applied Sciences (FI)
- P** Palo Alto Research Center (US)
Papiertechnische Stiftung (DE)
Profactor (AT)
- R** RISE Research Institutes of Sweden (SE)
- T** Tampere University (FI)
Technische Hochschule Nürnberg Georg Simon Ohm (DE)
Technische Universität Chemnitz (DE)
Technische Universität Darmstadt - IDD (DE)
Technische Universität Dresden - IAPP (DE)
Tekniker (ES)
TOPIC – Thailand Organic and Printed Electronic Innovation Center (TH)
- U** University of Applied Sciences Northwestern Switzerland (CH)
University of West Bohemia – RICE (CZ)
University of Bordeaux (FR)
University of Cambridge – Electrical Engineering Division (GB)
University of Manchester (GB)
University of Novi Sad – Faculty of Technical Sciences (CS)
University of Oulu (FI)
University of Pardubice (CZ)
- University of St. Andrews – Organic Semiconductor Centre (GB)
- V** Vito (BE)
VTT - Technical Research Centre of Finland (FI)
- W** WCPC - Swansea University (GB)
- Y** Yamagata University (JP)